

Figure 2

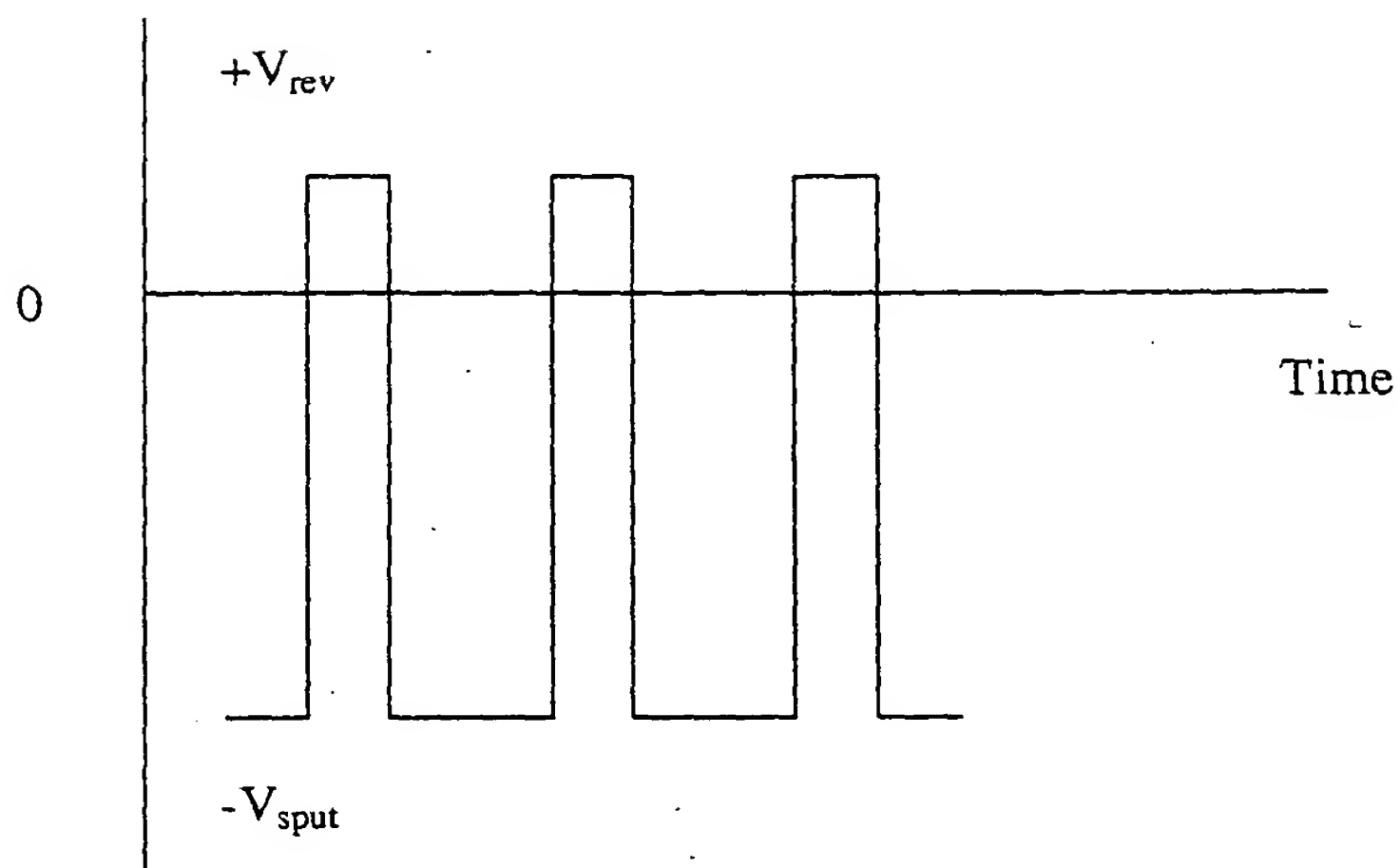


Figure 3

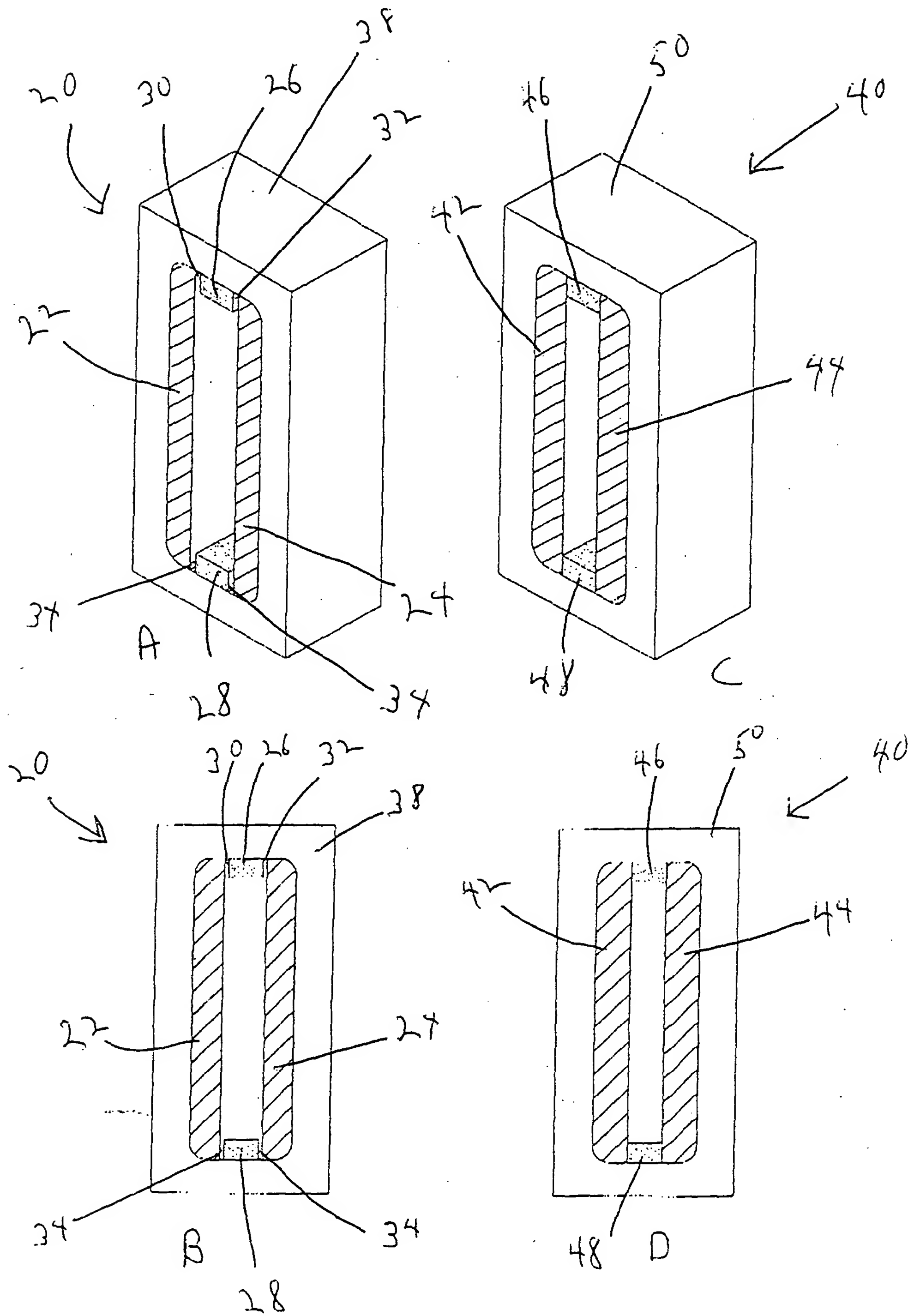


Figure 4

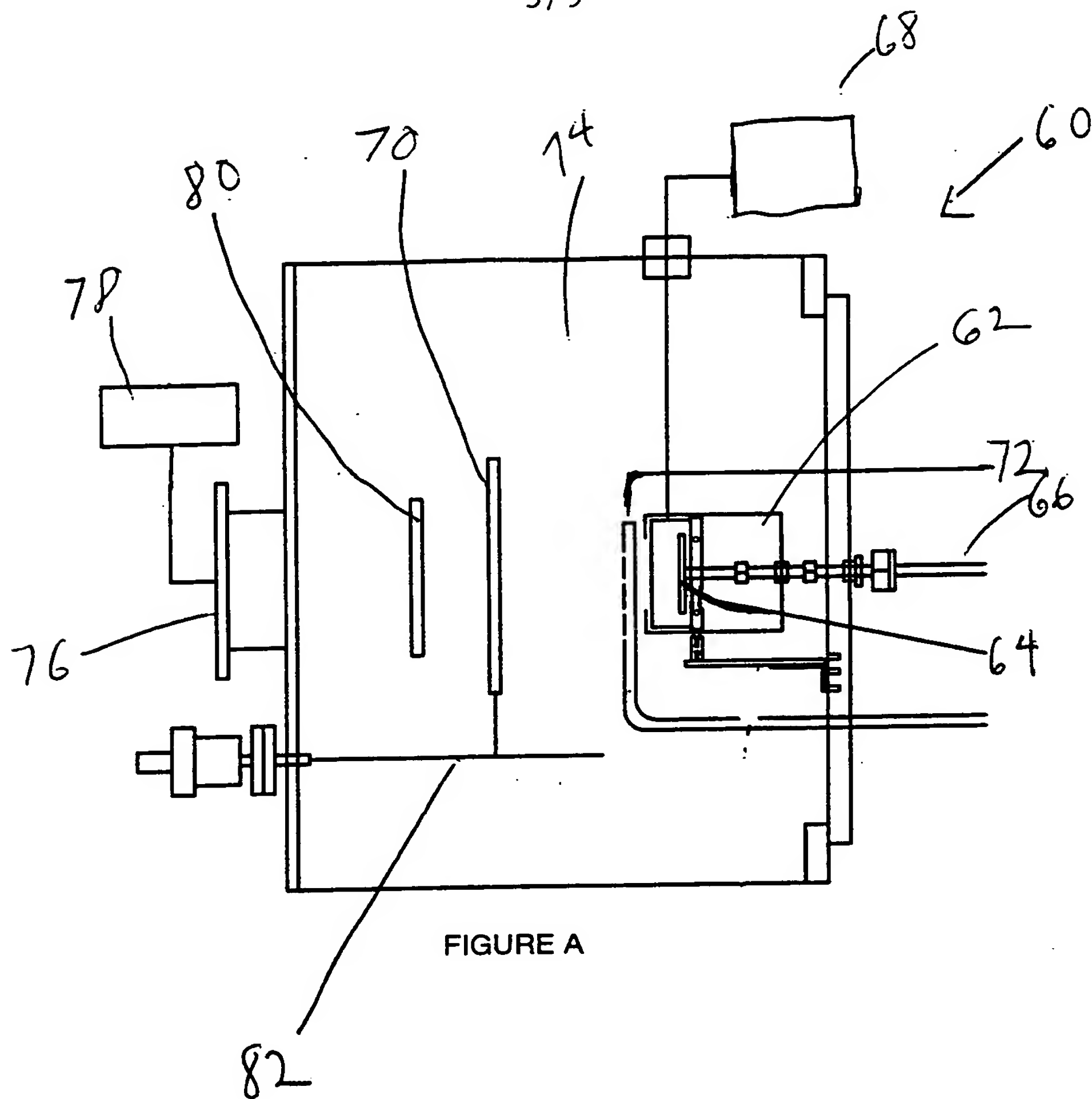


Figure 5A

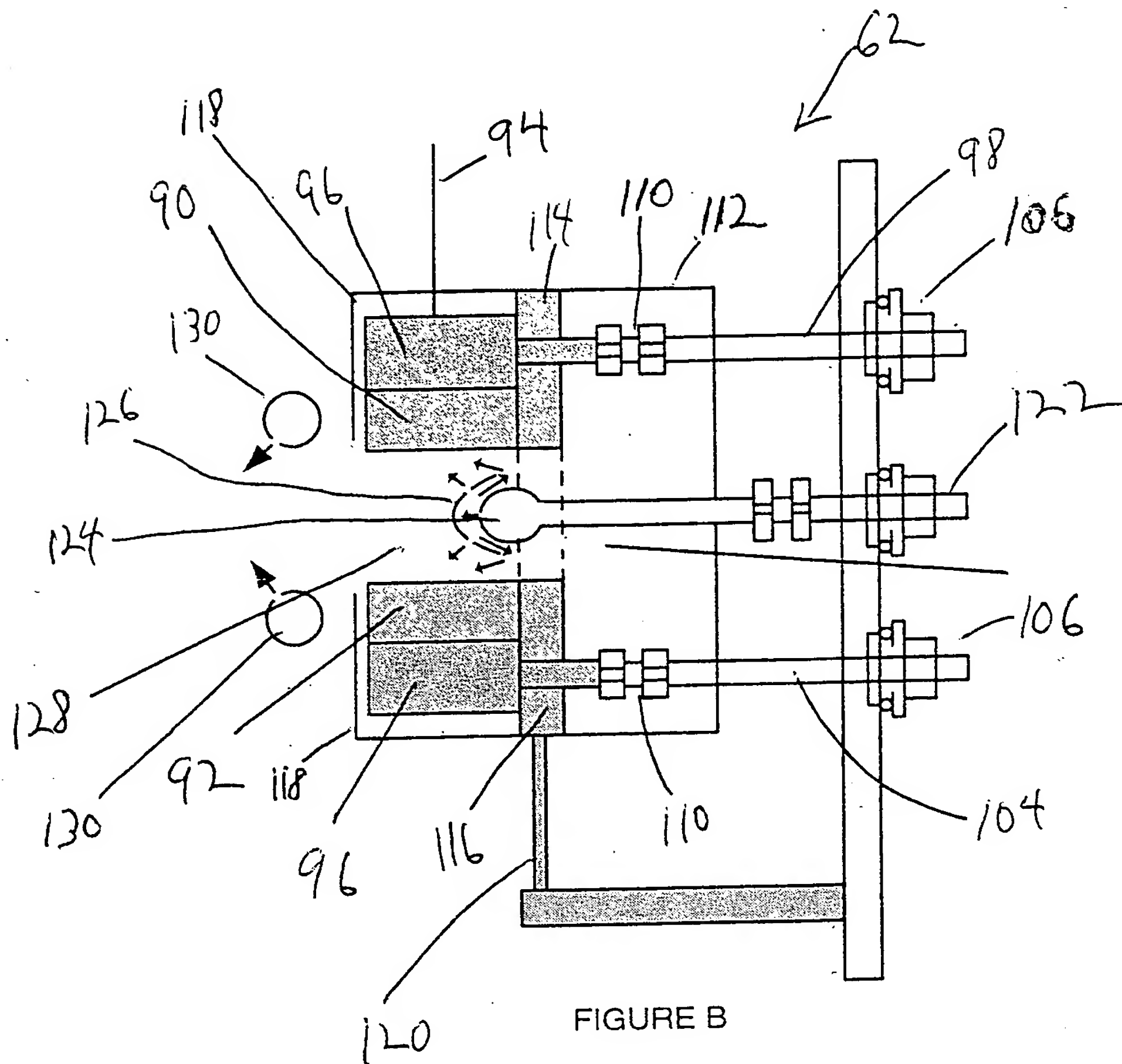
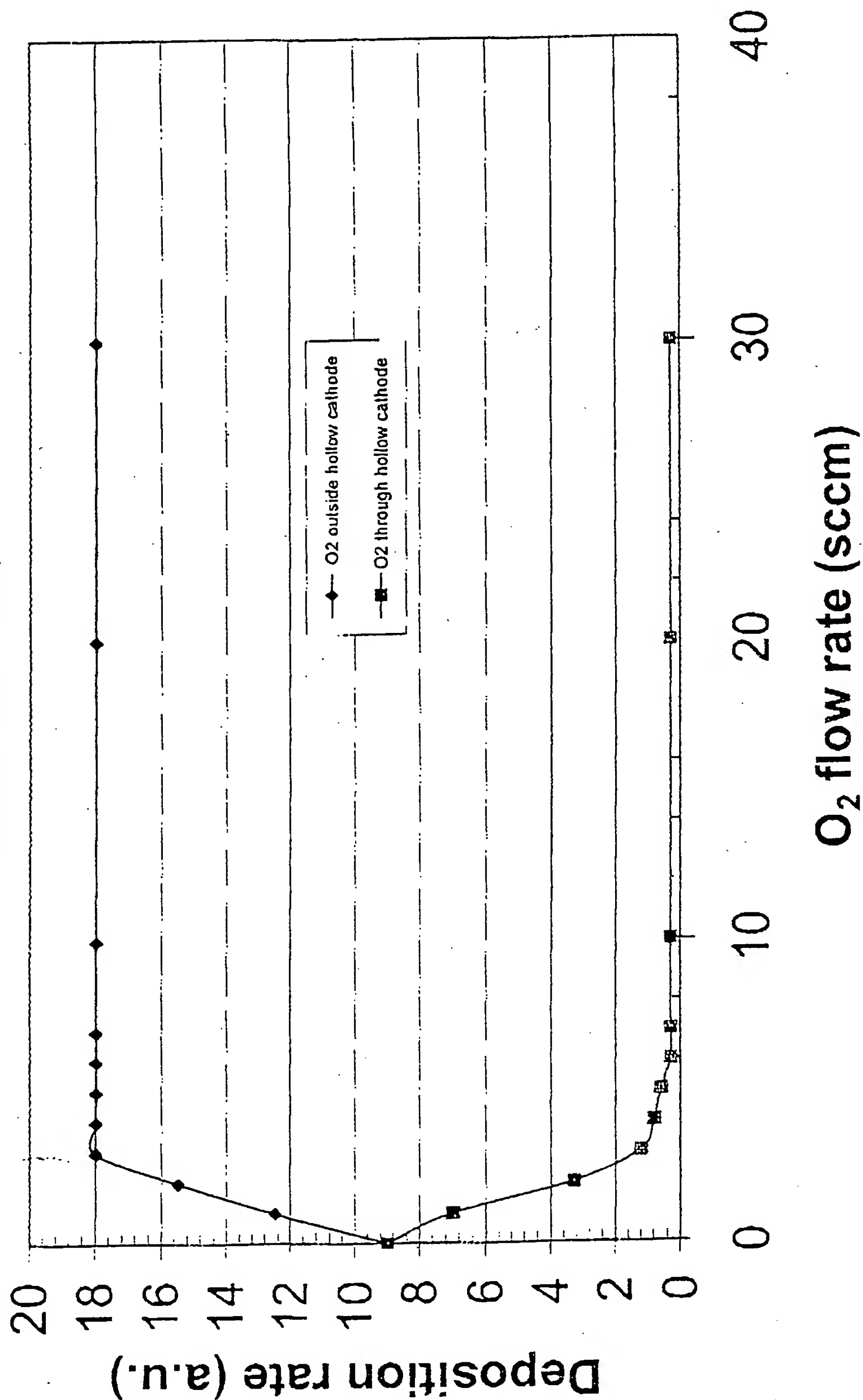


FIGURE B

Figure 5B

Figure 6

Comparison of deposition rate for O₂ injected outside the hollow cathode and for O₂ passing through the hollow cathode (Ar 4slm, 300W, 250mTorr)



Title: **HOLLOW CATHODE SPUTTERING APPARATUS AND RELATED METHOD**

First Named Inventor: **Alan E. Delahoy**

Application Serial No.: / Atty. Docket No.: **ENPI 0101 PUS**

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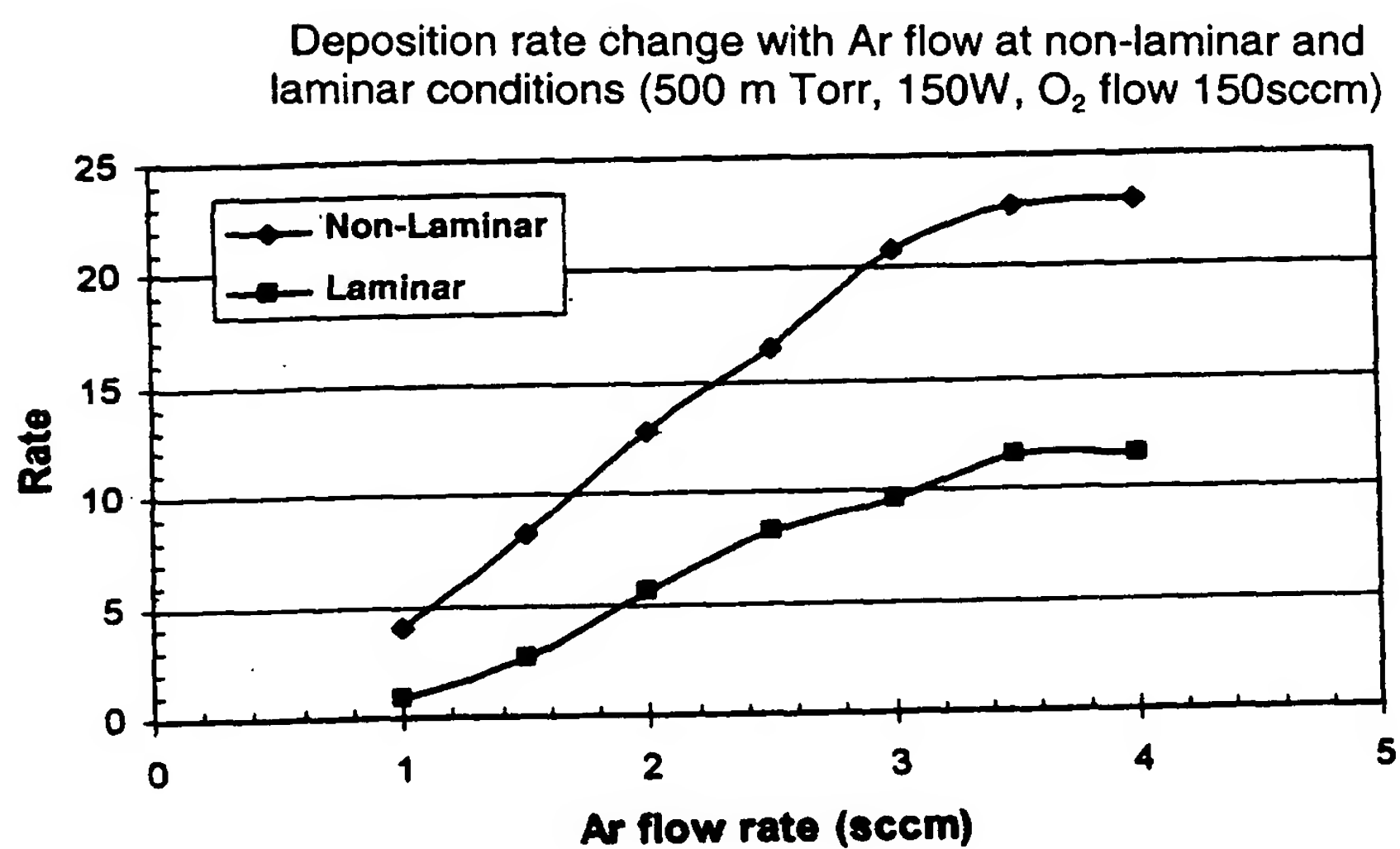


Figure 7

Film deposition rate vs O₂ flow rate with non-laminar and laminar
Ar flow (Al target, 300W, 500m Torr)

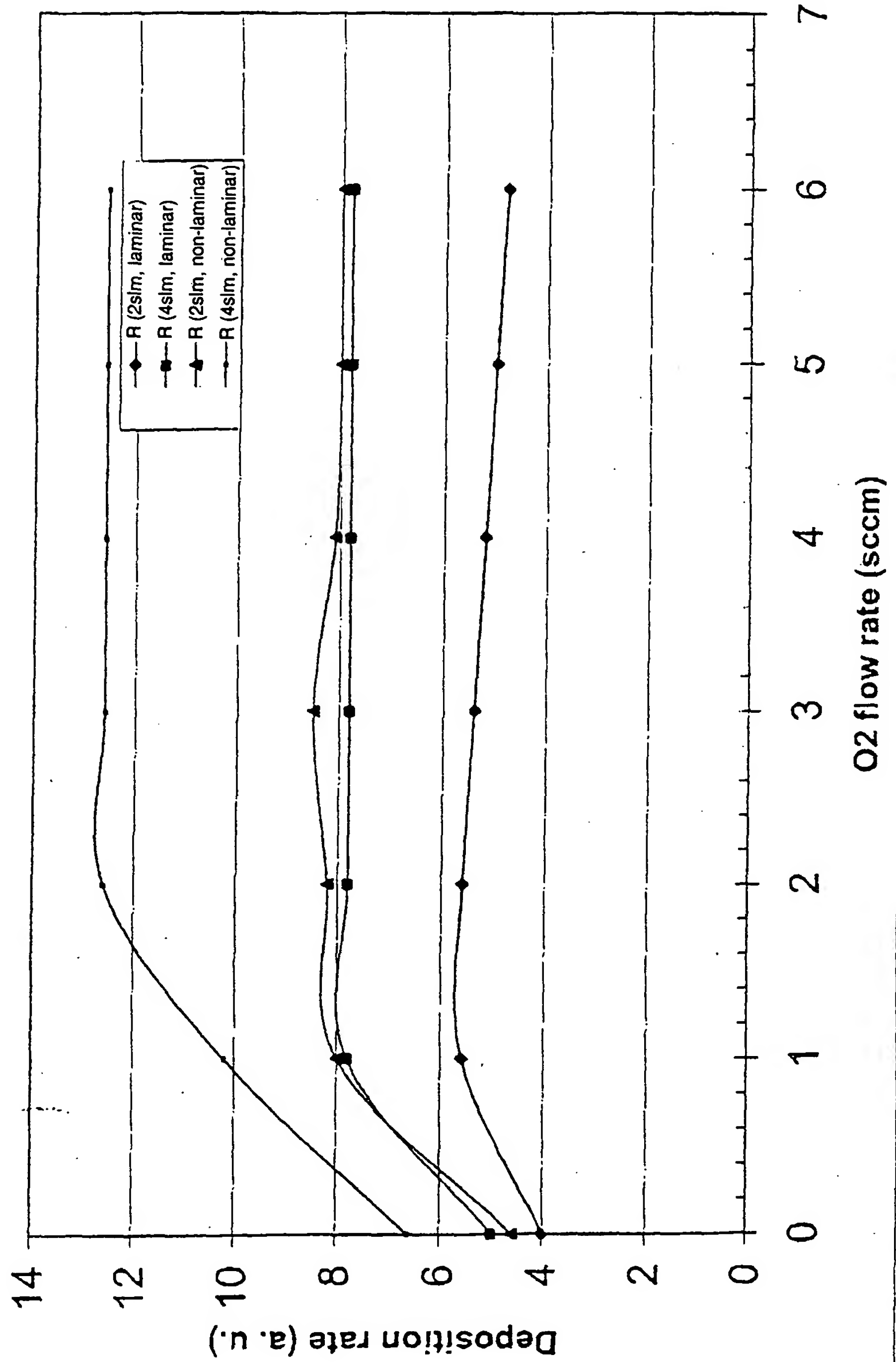


Figure 8